



Fine Pitch Bump Adapters

FEATURES

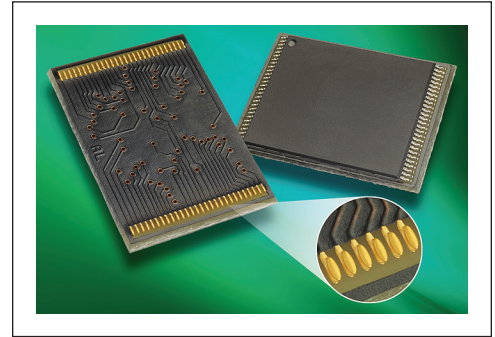
- Adapt to fine pitch footprints including TSSOPs and QFPs with pitches down to 0.4mm
- Features raised connection pads up to 0.010"
- Available in tape and reel for high speed SMT assembly
- Can be manufactured for RoHS compliance

GENERAL SPECIFICATIONS

- BOARD MATERIAL: 0.032 [0.81] thick FR-4 or Rogers 370 HR, with 1/2-oz. Cu traces, both sides
- PADS: finished with ENIG (Electroless Ni Immersion Au), NSMD
- TRACE WIDTHS/SPACE: 0.003 [0.076]
- OPERATING TEMPERATURE: 221°F [105°C] FR-4, 266°F [130°C] Pb-free

MOUNTING CONSIDERATIONS

- Solders to existing PCB footprints for QFPs, TSSOPs, and many other fine pitch devices down to 0.4mm



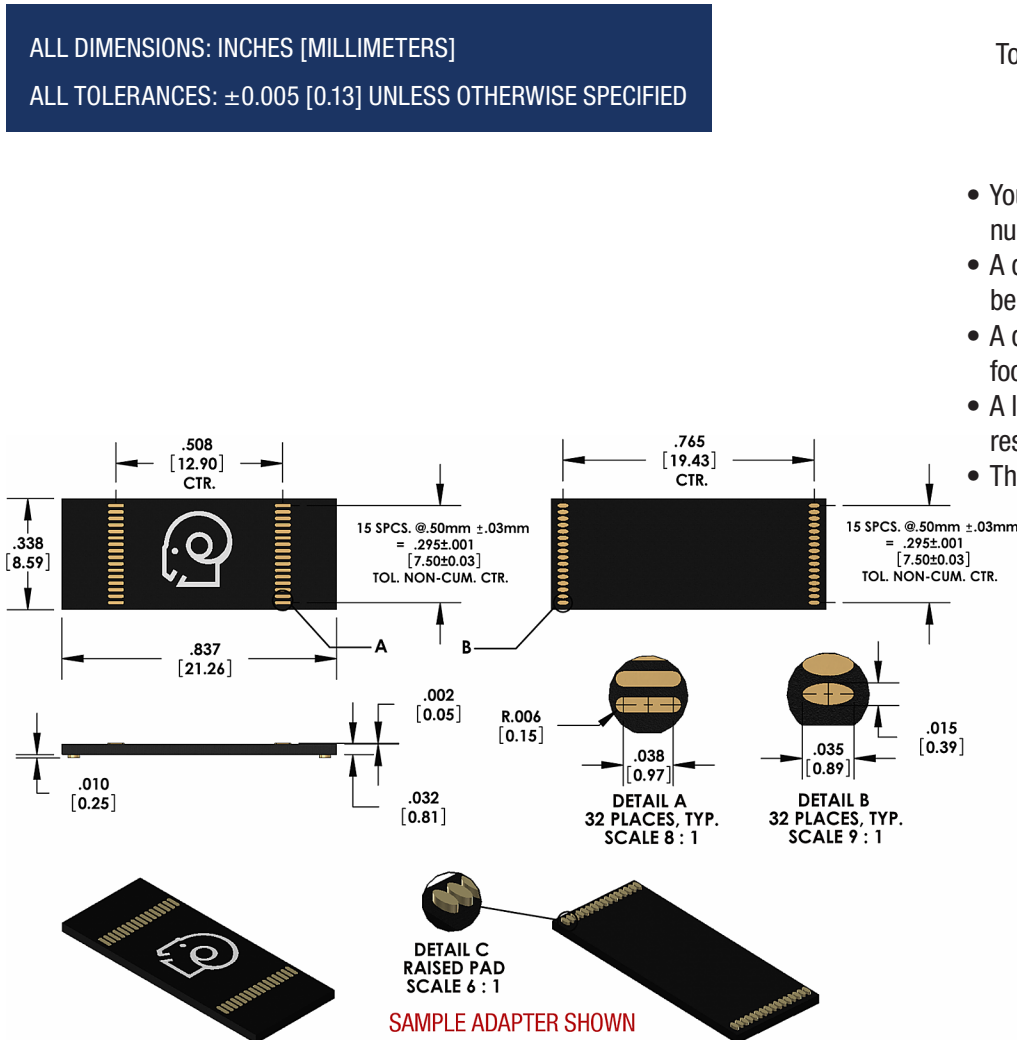
CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

To obtain a quote for a specific adapter, please email a request to info@arieselec.com

with the following information:

- Your name, company name, and telephone number
- A drawing or data sheet of the device to be placed on adapter (top image)
- A drawing or data sheet of the target footprint for the adapter (bottom image)
- A list of any other design parameters or restrictions that must be considered
- The quantity of adapters to be quoted



Bristol, PA 19007-6810 USA
TEL (215) 781-9956 • FAX (215) 781-9845
WWW.ARIESELEC.COM • INFO@ARIESELEC.COM